

However, ASM's management believes industry will continue to make investments related to enhanced technology like finer pad pitch wire bonder to meet the die shrink requirement, new chip-scale packaging challenge like QFN, and specific equipment to cope with the market demand of a package type.

As noted above, ASM's assembly equipment business is built on diversified products addressing different semiconductor assembly and packaging processes, serving wide application markets and strategically spread among IDMs and subcons, sizes and locations of customers. These stabilizing factors have dampened the industry fluctuations for ASM in the past, and together with our significantly improved market position in the last three years, should be helpful in ensuring a more resilient ASM that outperforms the industry.

Furthermore, this temporary soft market has its opportunities, allowing us time to make a smoother transition to the high performance AB339 Eagle wire bonder. It also permits potential customers to run evaluations, similar to 1998, giving ASM the opportunity to gain market share.

Naturally it is now prudent to control costs. However, we will also prepare ourselves sufficiently to meet the delivery challenge when the market rebounds strongly. With our strong balance sheet, while other competitors started to cut back, we intend to beef up our human resources to support customers in factory automation, process and packaging development, and speed up our technology and product development to both solidify and enhance our leading market position. Capital investment of US\$25 million is planned for the year.

Important new products will also provide support for our aggressive marketing program. Based on high performance control technology and linear motors, we are preparing a new generation IC die bonder capable of 200 and 300 mm. diameter wafers, 30% higher throughput than current model, with improved placement accuracy and bondline thickness; it will be ready for market launch in mid-2001. Similarly, after months of process and product development, our high performance, low cost flip chip bonder will be introduced during this year. To complete our modules for ASM's backend cluster, specifically for solder ball array packages, an integrated, small foot print ball placement, reflow and rinsing system is targeted for completion during 2001.

然而，ASM的管理層相信此行業仍需在某方面繼續投入資金，以確保技術之提升，例如採用微墊距之金線焊機以應付管芯收縮的需求，採用新型號之機器以迎合新包裝發展如QFN及其他特定包裝之市場需求等。

如上所述，ASM裝嵌設備業務建基於多元化的產品，能適合不同的半導體裝嵌及包裝程序之需要，為廣泛的應用市場提供服務，並策略性地涵括集成裝置製造商、包裝鑄造商，及大小不同地域的客戶。綜合此等因素之穩定作用，不但減低了業內波動對ASM的沖擊，並因此之故，集團的市場地位於過往三年內獲得顯著提升，更相信藉此動力應可令集團迅速於業內脫穎而出。

目前市場的暫時性放緩情況使我們有充足的過渡期以推廣性能卓越的AB339 Eagle焊線機，尤其能讓若干客戶在其廠房實地試用，正如一九九八年時一樣，令ASM藉此而增加其市場佔有率。

集團非常著重於控制成本。然而，我們已準備就緒去應付當市場出現強勁復甦時的付運需求。儘管其他競爭對手均減省人手，我們憑藉穩健的營運資金，將計劃加強人力資源的投入以支援客戶生產自動化、加工及包裝之發展。同時我們將加快技術及產品之發展以鞏固及加強在市場上的領導地位。來年資本性開支預計為二千五百萬美元。

重點新產品的推出將支持我們積極的市場推廣計劃。建基於功能卓越的操控技術及線性馬達之發展，我們正發展新一代集成電路管芯焊接機，改良了方位的準確性與焊線厚度，使這新一代的管芯焊接機能直接處理200及300mm直徑之晶片，較現有型號高出百分之三十的產量。此新型號之機種將於二零零一年年中推出市場。同樣地，經過數個月的加工及產品發展，我們高性能、低成本的覆晶焊接機將會於今年推出。此外，因應尤以為「焊珠排列包裝」之需要而設的一個綜合系統包括微細足跡焊珠放置、回焊及清洗程序之機械組合將於二零零一年推出，以完備ASM的後工序群組。

We have already provided technical support to customers in the QFN packaging development, designed and fabricated etched leadframes, solved their wire bonding problems, developed new processing modules (e.g. de-taping) and provided in-line automation solutions. Our intention is to create strategic partnerships with customers to have their integrated circuits (ICs) built on ASM leadframes and manufacturing processes qualified with ASM equipment.

The short-term market correction may prove to be ASM's golden opportunity to gain significant market share. We intend to capitalise on it and anticipate our shareholders will give us their full support.

#### **APPRECIATION**

Last year was a truly outstanding year for ASM. The huge revenue growth is a testament to the tremendous efforts put in by all our staff, who have met the challenge of ramping up our production so rapidly. The Group's Board gratefully acknowledges their dedication and diligence, and is confident that the solid achievements in year 2000 have laid the groundwork for future progress that will withstand market fluctuations.

**Arthur H. del Prado**  
Chairman  
12 February 2001

我們為顧客提供QFN包裝發展之技術支援，設計及生產蝕片引線框架，解決其線焊問題，發展新的加工工序(如除膜)及提供整線自動化解決方案等，旨在與顧客建立策略性合作夥伴關係，引導客戶以ASM的框架，生產設備及工序生產他們的集成線路產品。

市場短期之整固或可為ASM帶來增佔更大市場的黃金機會。我們將把握此機會，並期望會獲得股東們的全力支持。

#### **致謝**

去年ASM集團業績出眾，營業收益大幅增長，實有賴全體員工努力不懈應付挑戰，迅速提高生產力所致。對於大家盡忠職守、勤奮努力，集團董事會謹此致以衷心謝意！集團產品需求甚殷，董事會深信，集團在二零零零年取得的輝煌成就，已為未來業務增長奠定穩固基礎以抵禦市場之動盪。

主席  
**Arthur H. del Prado**  
二零零一年二月十二日